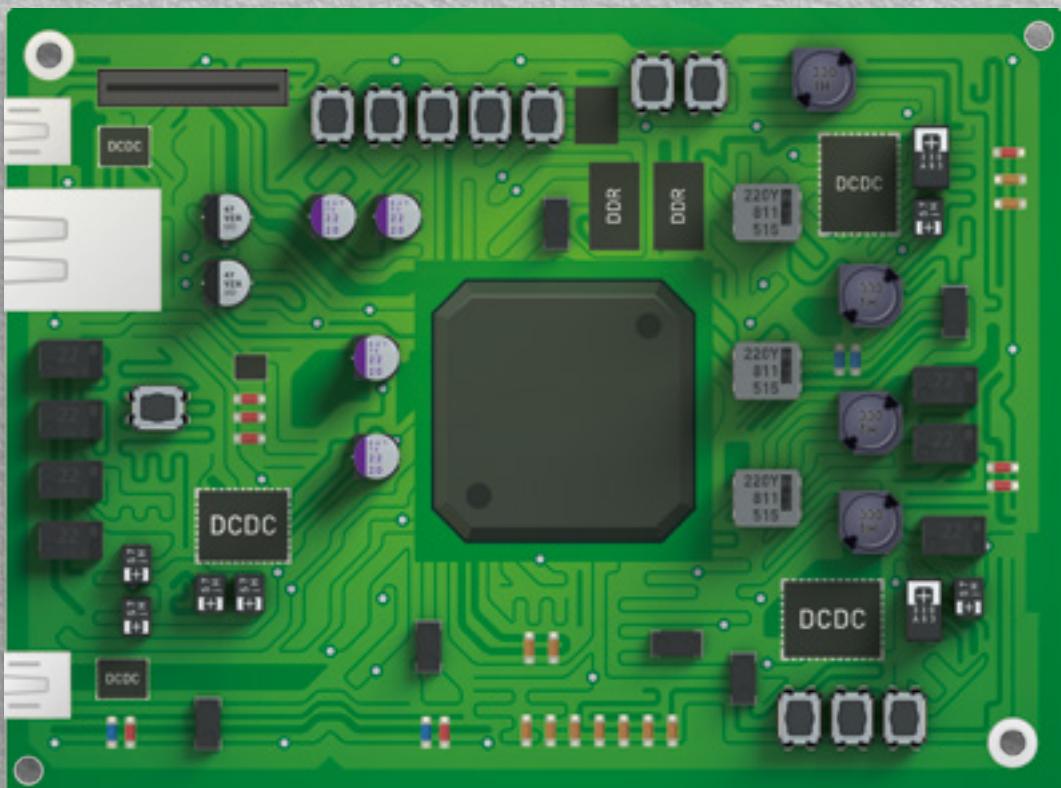


POLYMER CAPACITORS

Speed up your FPGA design



Lower Height

Higher Voltage

SP-Cap

AI Chip Type



Alternative to Tantalum

Super low ESR

POSCAP

TA Chip Type



Miniaturisation

Small case sizes

OS-CON

AI Solid Can Type



Long lifetime

High ripple current

Hybrid

AI Hybrid Can Type



High temperature

High capacitance

The next stage of low ESR capacitors, with high capacitance in small package

- > Widest polymer line-up with lowest ESR in the market
- > Global leader with local technical support
- > Cost optimisation & downsizing of reference solutions

POLYMER CAPACITORS

Speed up your FPGA design

Application Trend

- > High processing CPU / FPGA
- > Higher mounting density, hot spots
- > Longer life at elevated PCB temperature
- > High efficiency power supply design

Increasing Current

Capacitor Requirements

- > Low ESR, high capacitance
- > Small size
- > High voltage
- > Long endurance
- > Stable characteristics
- > Volume performance

Key Features

SP-Cap	Super low ESR Low profile
POSCAP	Small size High capacitance
OS-CON	High ripple current High voltage (100V)
Hybrid	High temperature Low LC

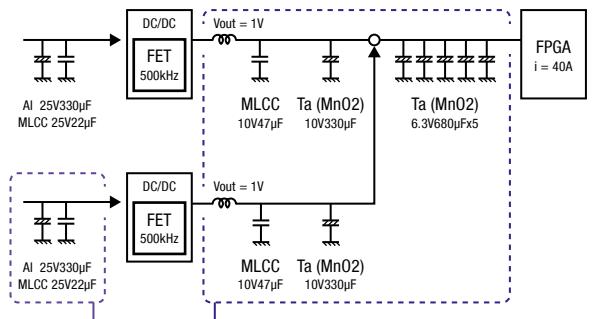
Example for Input/Output power circuit optimisation

Required Ripple Current (Ir)

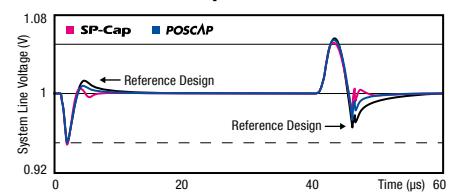
$\geq 2.76 \text{ Arms}$

$$(I_r) = I_x / (V_{in} - V_{out}) \times V_{out} / V_{in}$$

(peak 10A/phase)



Transient Response Simulation



Lifetime Extension

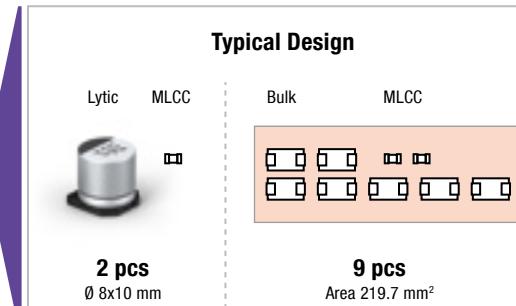
OS-CON

16V, 82μF
Size Ø 5x5.9 mm
Ripple current 3Arms
Lifetime 5000 h, 105°C
(equal to 50.000 h, 85°C)

Hybrid

25V, 100μF
Size Ø 6.3x7.7 mm
Ripple current 2Arms
Lifetime 10000 h, 105°C
(equal to 40.000 h, 85°C)

Typical Design



Space & Cost Saving

SP-Cap

	2V, 560μF ESR 3mΩ	1 pc
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Reduce ~85%

POSCAP

	each 2.5V, 220μF ESR 15mΩ	3 pcs
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